

ANTENNA PRODUCTS

DATA SHEET

**5010 Ceramic Chip Antenna
for Bluetooth/Wimax Application**

Feb, 2008 Ver.5

| | | | | | | | |
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| R&D | Print date 09/02/24 | | | | | | |
| | 5010 Ceramic Chip Antenna for Bluetooth/Wimax Application | | | CAN4311 851 XX 245 3K | | | June, 2008 v3 |
| | | | | | | | Sept, 2008 v4 |
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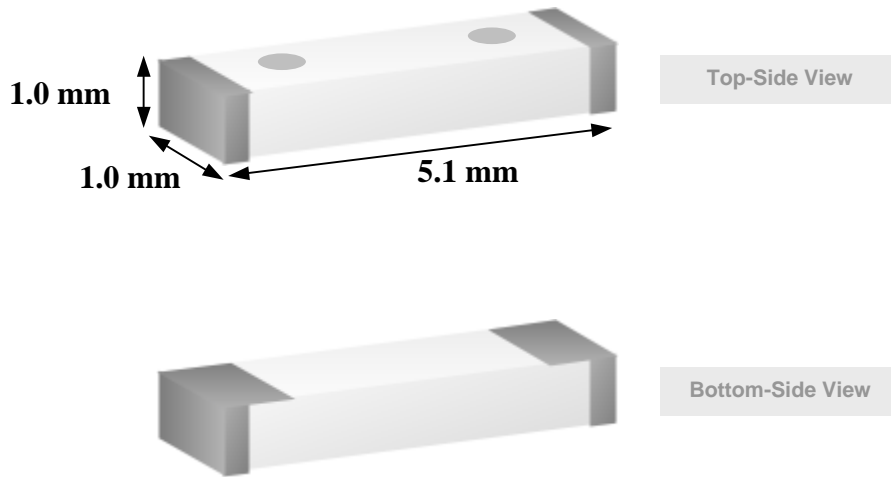
5010 Ceramic Chip Antenna for Bluetooth/Wimax Application

Quick Reference Data

| | |
|-------------------------------|---|
| Centre Frequency | 2.45 GHz |
| Bandwidth | 2.38 ~ 2.59 GHz |
| VSWR | 2.0 (Max.) |
| Polarization | Linear |
| Azimuth Beamwidth | Omni-directional |
| Peak Gain | 2.45 dBi |
| Impedance | 50Ω |
| Operating Temperature | -25~85 °C |
| Termination | Ni / Sn (Environmentally-Friendly Leadless) |
| Resistance to soldering heats | 260°C , 10sec. |
| Maximum Power | 1W |

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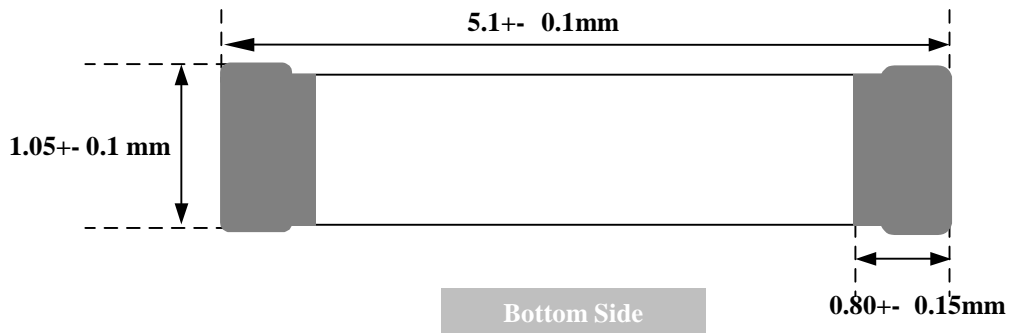
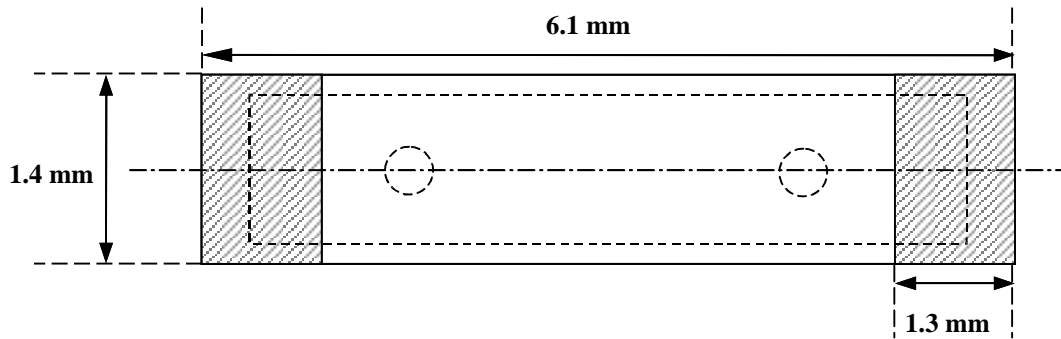
1. Mechanical Data (5.1 x 1x 1 mm³)



CAN4311851002453K

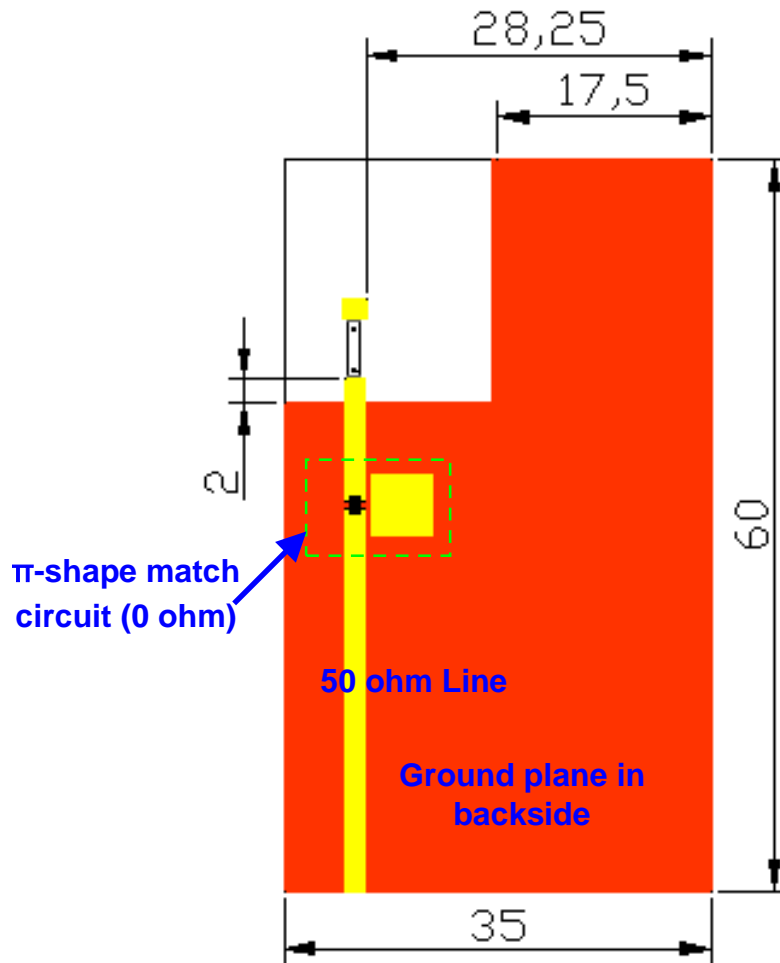
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2. Dimension of Footprint



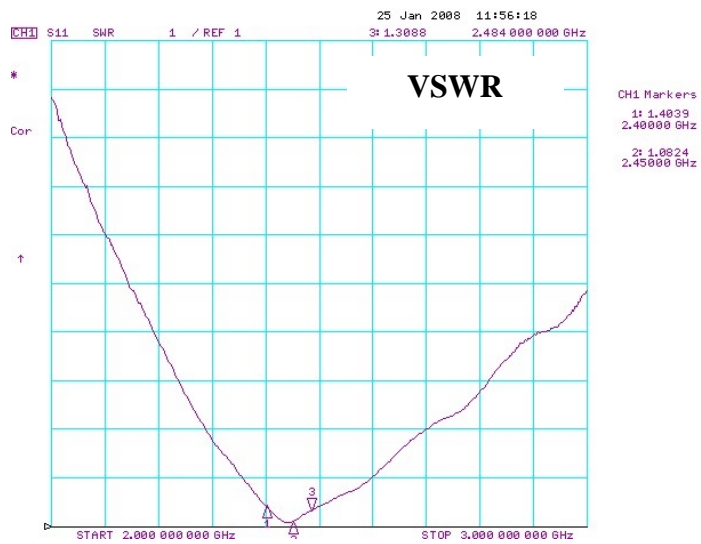
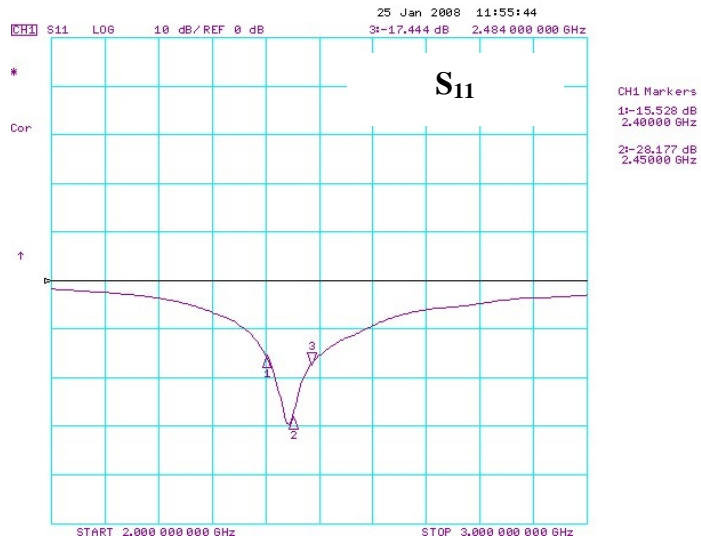
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3. Evaluation Board Dimension and Outlook



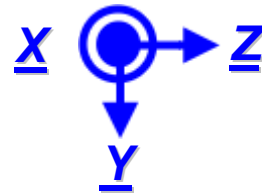
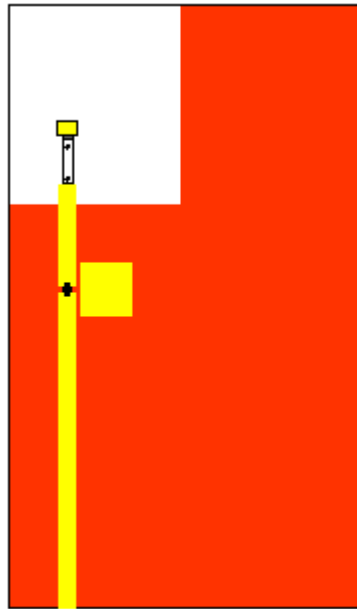
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4. Measured S-parameter



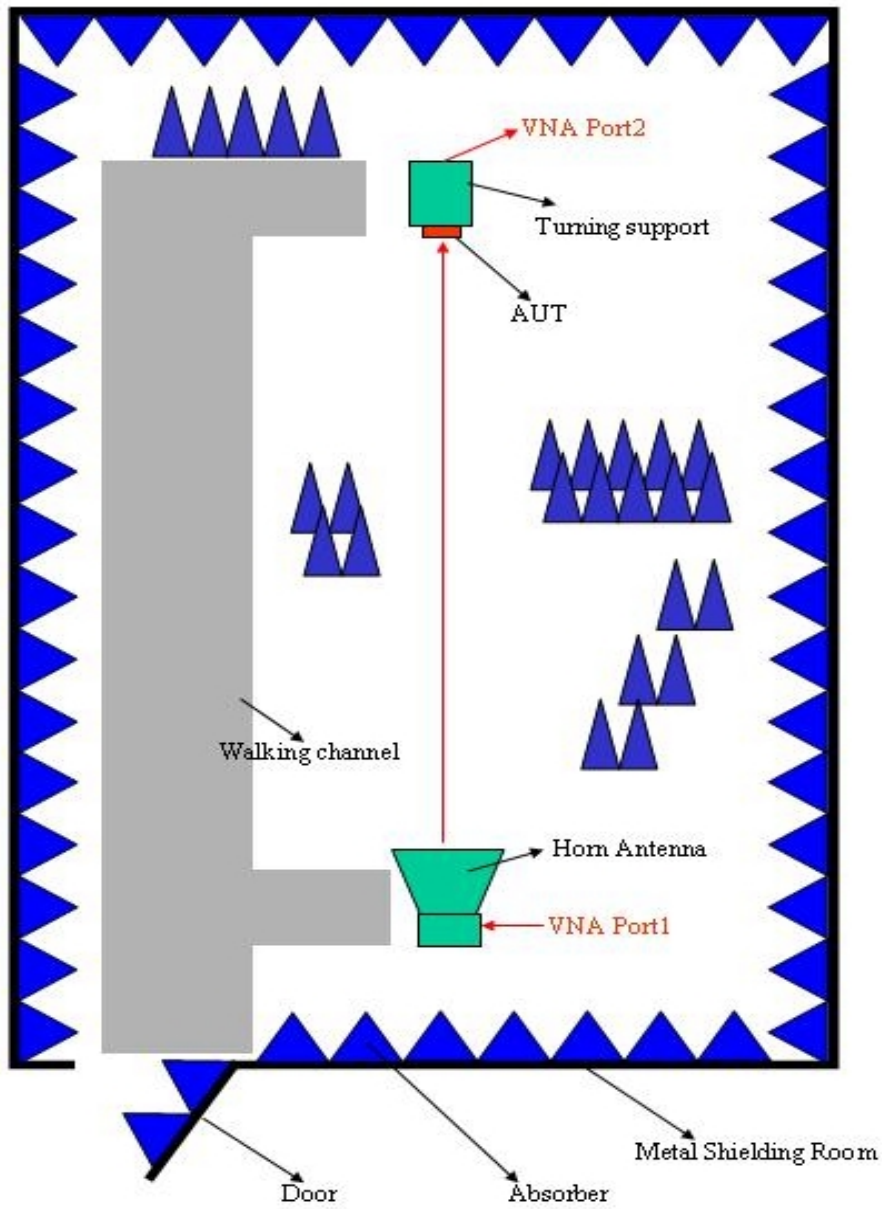
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5.The Definition of X-Y-Z Plane



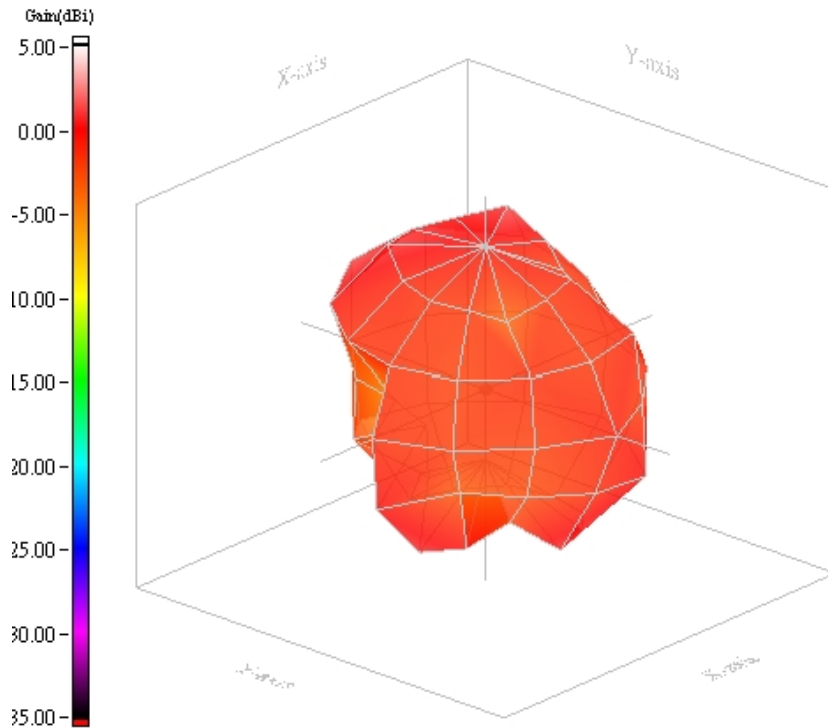
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6. The Environment of Antenna Radiation Pattern
Anechoic Chamber Dimension=10(m) × 6(m) × 6(m)



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7. Radiation Pattern



Max gain= 2.45dBi, at (60, 240)
 MEG (mean effective gain)= -1.14dBi
 Directivity(dB)= 3.59
 Efficiency= -0.84dB, 82.42%

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| Oscar Lu | Yageo Taiwan / High Frequency | | | | | |

8. Reliability Test

| IEC 384-10/ CECC 32 100 CLAUSE | IEC 60068-2 TEST METHOD | TEST | PROCEDURE | REQUIREMENTS |
|---|-------------------------------|---------------------------------------|---|---|
| 4.4 | | Mounting | The antenna can be mounted on printed-circuit boards or ceramic substrates by applying wave soldering, reflow soldering (including vapour phase soldering) or conductive adhesive | No visible damage |
| 4.5 | | Visual inspection and dimension check | Any applicable method using $\times 10$ magnification | In accordance with specification (chip off 4mm) |
| 4.6.1 | | Antenna | Central Frequency at 20 °C | Standard test board in page 4 |
| 4.8 | | Adhesion | A force of 3 N applied for 10 s to the line joining the terminations and in a plane parallel to the substrate | No visible damage |
| 4.9 | | Bond strength of plating on end face | Mounted in accordance with CECC 32 100, paragraph 4.4 | No visible damage |
| | | | Conditions: bending 0.5 mm at a rate of 1mm/s, radius jig. 340 mm, 2mm warp on FR4 board of 90 mm length | No visible damage |
| 4.10 | 20(Tb) | Resistance to soldering heat | 260 \pm 5 °C for 10 \pm 0.5 s in a static solder bath | Satisfy the original electrical specification after soldering. |
| | | Resistance to leaching | 260 \pm 5 °C for 30 \pm 1 s in a static solder bath | Using visual enlargement of $\times 10$, dissolution of the termination shall not exceed 10% |

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| IEC 384-10/ CECC 32 100 CLAUSE | IEC 60068-2 TEST METHOD | TEST | PROCEDURE | REQUIREMENTS |
|--------------------------------|-------------------------|-----------------------------|--|---|
| 4.11 | 20(Ta) | Solderability | Zero hour test, and test after storage (20 to 24 months) in original atmosphere; un-mounted chips completely immersed for 2 ± 0.5 s in $235 \pm 5^\circ\text{C}$. | The termination must be well tinned, at least 75% is well tinned at termination |
| 4.12 | 4(Na) | Rapid change of temperature | -25°C (30 minutes) to $+85^\circ\text{C}$ (30 minutes); 100 cycles | No visible damage Central Freq. Change $\pm 6\%$ |
| 4.14 | 3(Ca) | Damp heat | 500 ± 12 hours at 60°C ; 90 to 95 % RH | No visible damage 2 hours recovery Central Freq. Change $\pm 6\%$ |
| 4.15 | | Endurance | 500 ± 12 hours at 85°C ; | No visible damage 2 hours recovery Central Freq. Change $\pm 6\%$ |

■ **Notice (shipping and storage during transportation)**

In order to ensure some quality, it is suggested to follow the condition during shipping :

- Temperature : $-40\sim 70^\circ\text{C}$
- Humidity : 45~75%

■ **Notice (storage condition)**

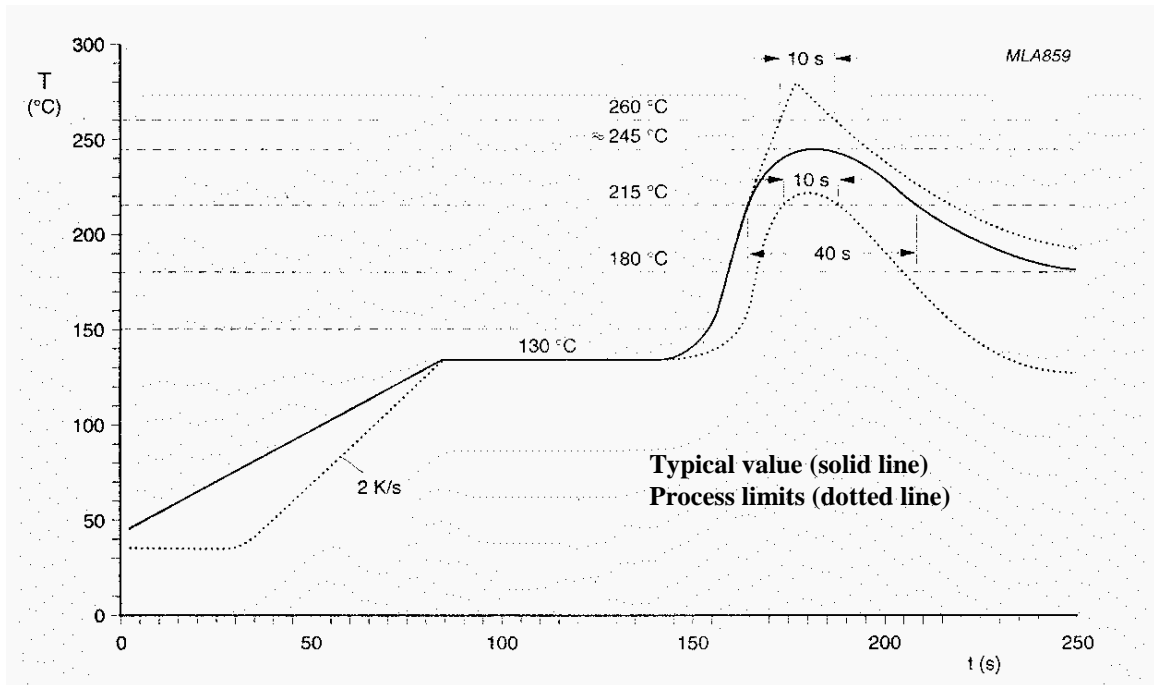
In order to ensure the solderability of the termination, it is suggested to follow the condition for storage :

- Temperature : $15\sim 30^\circ\text{C}$
- Humidity : 45~75%
- Prevent corrosive gas (SO_2 , NO_x , NH_3 , Cl_2 , ..etc)
- It is better to use products within 6 months. Solderability should be confirmed again if exceed 6 months.

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9. Soldering Condition (Suggestion)

* Customers should alter the profile according to realistic tin paste in use.



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10. Ordering Information

The antennas may be ordered by using the Yageo ordering code. These code numbers can be determined by the following rules:

CAN43 11 8 51 04 245 3K

Family Code

CAN 43 = Yageo Part No. for Antenna

Packing Type Code

11 = 180 mm/ 7" reel , blister taping

Materials Code

8 = High Frequency Material (White)

Size Code

51 = 5.0 * 1.0 * 1.0 mm

Antenna type

00 = Normal type

01 = type 01

02 = type 02

03 = type 03

04 = type 04

05 = type 05

06 = type 06

07 = type 07

08 = type 08

Working Frequency

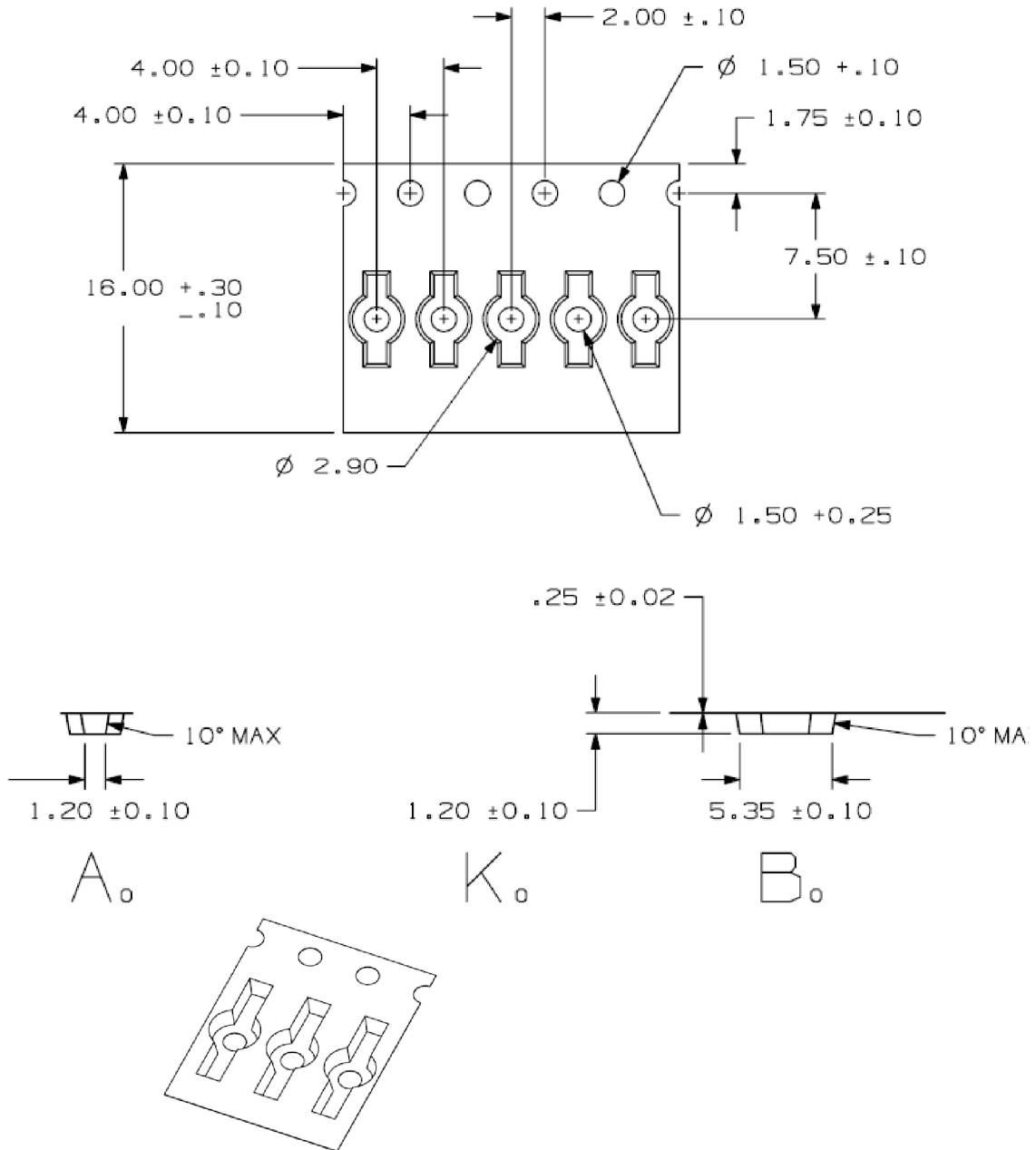
245 = 2.45 GHz

Packing Type Code

3K = 3000 pcs for taping per reel

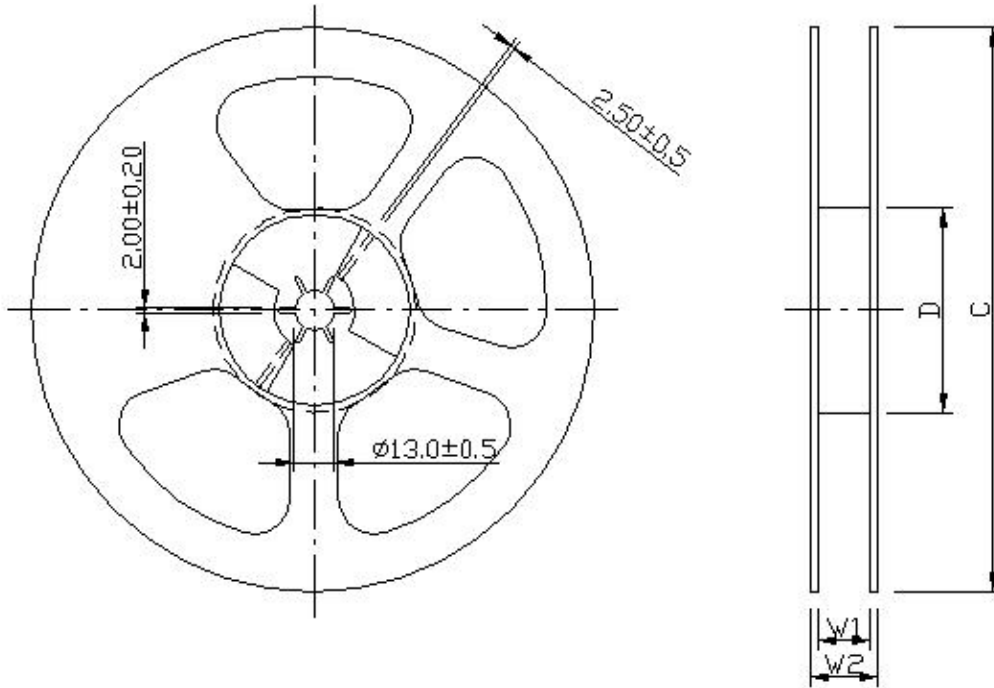
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11. Taping Blister Tape



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12. Taping Reel - 7"(180mm) Specifications



| Product size code | Units per Reel | Tape Width (mm) | C (mm) | D (mm) | W ₁ (mm) | W ₂ (mm) |
|-------------------|----------------|-----------------|-----------|--------|---------------------|---------------------|
| Antenna | 1000 | 16 | 180.0±1.0 | 62±0.5 | 16.0±1.0 | 20.5±1.0 |

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11. Tape Revision Control:

| Revision | Date | Content | Remark |
|----------|------------|---------------------------------------|--------|
| V1 | Jan, 2008 | New Issue | |
| V2 | May, 2008 | Increase type 1~4, 8. | |
| V3 | June, 2008 | Increase normal type | |
| V4 | Sept, 2008 | To modify the spec of end-termination | |
| V5 | Feb,2009 | To modify the suggestion of footprint | |
| | | | |

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